

Samtec Features Latest 32GT/s Interconnect Solutions at PCI-SIG® Developers Conference 2019

New Albany, IN: Samtec Inc., a privately held \$822 MM global manufacturer of a broad line of electronic interconnect solutions, will showcase and demonstrate their latest high-performance interconnect and technologies at the PCI-SIG® Developers Conference 2019.

Samtec high-speed technologies for Silicon-to-Silicon optimization will be on display, including new high-speed, high-bandwidth optical, board-to-board and cable-to-board interconnects. 56 Gbps PAM4 and 32 GT/s product demonstrations and technical sessions will also be highlighted.



Demonstrations:

- **Scalable 32 GT/s Silicon Test Platform:**
Demonstration of configurable, next-generation GPU-based system combining a cable mesh backplane (AcceleRate® Slim Body Cable Assemblies) and next-generation Edge Rate® High-Speed Edge Card Connector topologies.
- **56 Gbps PAM4 Active Product Demonstrator:**
The 56 Gbps PAM4 Active Product Demonstrator showcases Samtec's comprehensive portfolio of high-performance interconnect in a typical data center chassis application.

Technical Sessions:

1:00 PM Tuesday, June 18, 2019 - Kevin Burt Sr. System Architect – Optical Systems

- **Enable PCI Express® (PCIe®) 5.0 System Design with Ethernet Architectures:**
As PCIe technology data rates increase to 32 GT/s, system SI becomes critical. As other interfaces (Ethernet, InfiniBand, etc.) achieve higher data rates, opportunities exist to leverage industry-wide techniques that optimize power, thermal efficiency and cost-effectiveness across the system. Samtec will explore options enabling PCIe technology system architects to achieve similar results.

11:30 AM Wednesday, June 19, 2019 - Steve Krooswyk Sr. SI Engineer

- **2GT/s Test Platform for AI and ML Implementations:**
Confident SI evaluation in emerging AI/ML forms factors and cable mesh topologies requires realistic interconnect stress. Current length extenders and multiple PCIe topologies present challenges for adequate SI evaluation. Samtec will present the advantages of next-generation Scalable 32 GT/s Silicon Test Platforms.

The demonstrations can be seen in the Samtec booth at PCI-SIG Developers Conference 2019 at the Santa Clara (CA) Convention Center. The conference is June 18-19, 2019.

For more information on the Samtec High-Performance Interconnect Portfolio, please visit www.samtec.com/s2s or e-mail SIG@samtec.com.

About Samtec, Inc.:

Founded in 1976, Samtec is a privately held, \$822MM global manufacturer of a broad line of electronic interconnect solutions, including High-Speed Board-to-Board, High-Speed Cables, Mid-Board and Panel Optics, Precision RF, Flexible Stacking, and Micro/Rugged components and cables. Samtec Technology Centers are dedicated to developing and advancing technologies, strategies and products to optimize both the performance and cost of a system from the bare die to an interface 100 meters away, and all interconnect points in between. With 40+ international locations and products sold in more than 125 different countries, Samtec's global presence enables its unmatched customer service. For more information, please visit <http://www.samtec.com>.

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